

What is claimed is;

1. A semiconductor device having a two-dimensional barcode pattern for information management provided at each of chips arrayed on a wafer surface as chip ID information.

2. A semiconductor device according to claim 1, wherein:

said chip ID information includes chip information inherent to each chip.

3. A semiconductor device according to claim 1, wherein:

said chip ID information is projected and exposed using a liquid crystal mask that is capable of changing a light transmitting pattern for each exposure.

4. A semiconductor device having a two-dimensional barcode pattern for information management provided on a lead frame to which semiconductor chips are bonded as frame ID information.

5. A semiconductor device according to claim 4, wherein:

said frame ID information includes chip positional information corresponding to chips within said frame.

6. A semiconductor device according to claim 4, wherein:

said frame ID information is made to correspond to chip ID information provided as a two-dimensional barcode pattern for information management for each chip.

7. A semiconductor device having a two-dimensional barcode pattern for information management provided at an

outer surface of resin-sealed semiconductor chip as product ID information.

8. A semiconductor device according to claim 7, wherein:

said product ID information includes additional information corresponding to individual chips that are resin sealed.

9. A semiconductor device according to claim 7, wherein:

said product ID information ~~is made to correspond~~ ^{corresponds} to chip ID information provided as a two-dimensional barcode pattern for information management for each chip.

10. A semiconductor device according to claim 7, wherein:

said product ID information ~~is made to correspond~~ ^{corresponds} to frame ID information provided as a two-dimensional barcode pattern for information management on a lead frame to which semiconductor chips are bonded.

11. An information management system for semiconductor devices that implements management of information related to said semiconductor devices separately for individual semiconductor devices comprising:

chip ID information provided as a two-dimensional barcode pattern for information management for each chip;

a read device that reads said chip ID information; and

a management unit that registers said chip ID information thus read and manages individual semiconductor manufacturing processes based upon said chip ID information thus registered.

12. An information management system for semiconductor

devices according to claim 11, wherein:

said chip ID information is made to correspond to mapping data obtained during a probing process.

13. An information management system for semiconductor devices according to claim 11, wherein:

said chip ID information is projected and exposed using a liquid crystal mask that is capable of changing a light transmitting pattern for each exposure.

14. An information management system for semiconductor devices that implements management of information related to said semiconductor devices separately for individual semiconductor devices comprising:

frame ID information provided as a two-dimensional barcode pattern for information management on a lead frame to which semiconductor chips are bonded;

a read device that reads said frame ID information;
and

a management unit that registers said frame ID information thus read and manages individual semiconductor manufacturing processes based upon said frame ID information thus registered.

15. An information management system for semiconductor devices according to claim 14, wherein:

said frame ID information is made to correspond to chip ID information provided as a two-dimensional barcode pattern for information management for each chip.

16. An information management system for semiconductor devices that implements management of information related to said semiconductor devices separately for individual semiconductor devices comprising:

product ID information provided as a two-dimensional barcode pattern for information management at

an outer surface of resin-sealed semiconductor chips;

a read device that reads said product ID information; and

a management unit that registers said product ID information thus read and manages a product shipping process based upon said product ID information thus registered.

17. An information management system for semiconductor devices according to claim 16, wherein:

said product ID information ~~is made to correspond~~ to chip ID information provided as a two-dimensional barcode pattern for information management for each chip.

18. A semiconductor device according to claim 16, wherein:

said product ID information ~~is made to correspond~~ to frame ID information provided as a two-dimensional barcode pattern for information management on a lead frame to which semiconductor chips are bonded.

19. An information management system for semiconductor devices according to claim 16, wherein:

said product ID information that ~~is~~ registered is made to ~~correspond~~ to manufacturing process history information corresponding to each chip.

20. An information management system for semiconductor devices according to claim 16, wherein:

said product ID information that ~~is~~ registered is made to ~~correspond~~ to claim information regarding claims made in the field after product shipment.